

**AMENDMENT TO THE CLAIMS**

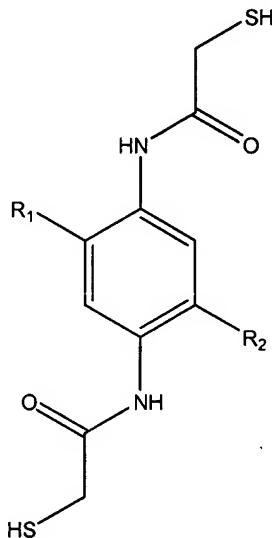
Please amend the claims without prejudice, without admission, without surrender of subject matter, and without any retention of creating any estoppel as to equivalents, as follows.

Claims 1-17 (cancelled)

Claims 18-22 (cancelled - not entered)

Claim 23 (new)

23. A multifunctional linker molecule which is selected from the group consisting of 1,4-dimercaptoaceamidobenzene of the formula:



wherein R<sub>1</sub> and R<sub>2</sub> are independently selected from CH<sub>3</sub> and/or Cl, 1,4-dimercaptoacetamidocyclohexane, 1,4-dimercaptoacetamido-9,10-anthraquinone, 1,5-dimercaptoacetamido-9,10-anthraquinone, 1,8-dimercaptoacetamidoctane, or 1,4-dithiocarbamatocyclohexane.

Claim 24 (new)

24. A 1-, 2- or 3-dimensional assembly of nanostructured units comprising a multifunctional linker according to claim 23, wherein the conductivity of the assembly is determined by the structure of the multifunctional linker.

Claim 25 (new)

25. The 1-, 2- or 3-dimensional assembly according to claim 24, wherein the nanostructured units are selected from the group consisting of nanoparticles, semiconductors, core/shell semiconductor nanoparticles, nanowires, nanotubes, nanobelts and electrodes.

Claim 26 (new)

26. The 1-, 2- or 3-dimensional assembly according to claim 25, wherein the assembly is in the form of a thin film of interconnected nanostructured units.

Claim 27 (new)

27. A 1-, 2- or 3-dimensional assembly of nanostructured units comprising a multifunctional linker which is 1,4-dithiocarbamatobenzene.

Claim 28 (new)

28. A method of manufacturing self-assembled electronic circuit elements, electrodes and metal coatings, comprising the step of utilizing the 1-, 2- or 3-dimensional assembly of claim 23.

Claim 29 (new)

29. A method of manufacturing self-assembled electronic circuit elements, electrodes and metal coatings, comprising the step of utilizing the 1-, 2- or 3-dimensional assembly of claim 27.